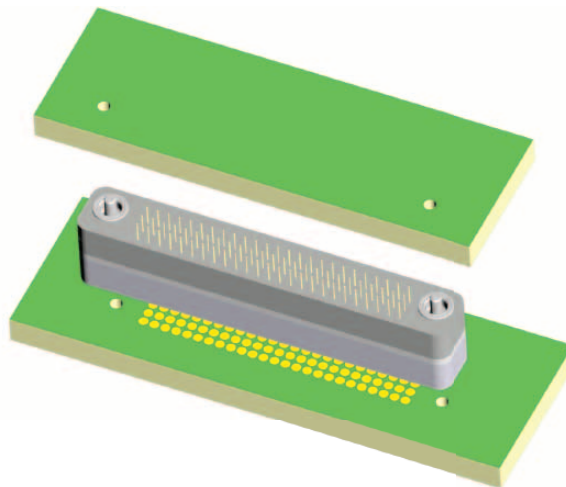




The RZ family of high-density, board-to-board or flex circuit stacking applications is unique, offering users a reliable one-piece contact system. Its solder-less interconnect is compressed or “sandwiched” under pressure between parallel printed wiring boards or between a printed wiring board and other electronic components such as an IC or multichip module.

- 0.050” staggered grid array
- Up to 400 contacts per square inch
- BeCu contacts for reliable mating
- Standard heights from 0.100” to 0.350”
- Custom configurations available to meet your specific design needs.





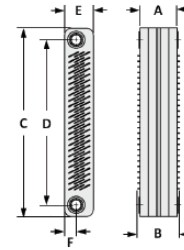
**Vertical Compression (Z-axis),
Open-Pin Field**

Contact spacing: 0.050" (1.27 mm)

A high-density, open-field, vertically-compressed connector utilizing a patented z-axis contact system configured for between-board (board-to-board) compression applications.

DIMENSIONS

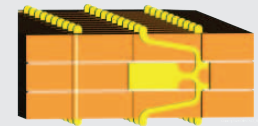
COLUMNS	C	D
10	0.952	0.742
15	1.202	0.992
20	1.452	1.242
25	1.702	1.492
ROWS	E	F
2	0.210	0.105
3	0.260	0.105
4	0.310	0.155
5	0.360	0.155
6	0.410	0.205
7	0.460	0.205



HARDWARE HEIGHT (A)	CONTACT HEIGHT (B)
0.100	0.120
0.150	0.170
0.200	0.230
0.250	0.280
0.300	0.330
0.350	0.380

Sample Part Number Format: RZ250-320-115-1000

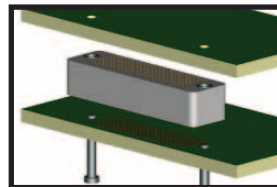
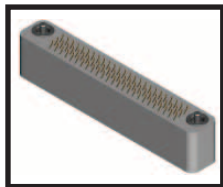
RZ								
SERIES Vertical (Z-Axis) Compression Multi-Rows 0.050" Spacing Open-Field	HEIGHT 100 – 0.100" 150 – 0.150" 200 – 0.200" 250 – 0.250" 300 – 0.300" 350 – 0.350"	ROWS 2 – 2 Rows 3 – 3 Rows 4 – 4 Rows 5 – 5 Rows 6 – 6 Rows 7 – 7 Rows	COLUMNS 10 – 10 Columns 15 – 15 Columns 20 – 20 Columns 25 – 25 Columns	CONTACT 11 – Double compression	PLATING 5 – 50 μ" Au 3 – 30 μ" Au	HARDWARE 10 – Ø.090" Thru-hole 20 – Ø.050" Guide pin	TYPE 00 – No polarization	VARIATION Blank – None XXX – Consult factory



PLEASE CONSULT THE AIRBORN WEBSITE FOR THE LATEST REVISION OF THIS DOCUMENT PRIOR TO BEGINNING ANY DESIGN WORK.

MATED HEIGHT

Mated height is defined as the space between the hardware clamping surfaces (top hardware surface to bottom hardware surface.) See Table 1.



SI DATA – Differential 100 Ohm

1	Diff. Insertion Loss	3.0 GHz @ -3 dB
2	Diff. Return Loss	1.0 GHz @ -20 dB
3	NEXT	2.0 GHz @ -50 dB
4	FEXT	2.0 GHz @ -48 dB

MATERIALS and FINISHES

Contact: BeCu C17200 per ASTM B194 (brush alloy 190)
 Contact Finish: Gold per ASTM B488 over nickel per SAE AMS-QQ-N-290
 Molded Insulator: Glass-filled polyphenylene sulfide (PPS) per MIL-M-24519
 Hardware: Stainless steel per ASTM A582/582M, passivated per SAE AMS-2700

NOTE: AirBorn can manufacture special configurations to your exact specifications.

PERFORMANCE

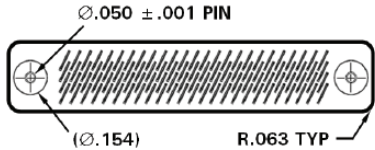
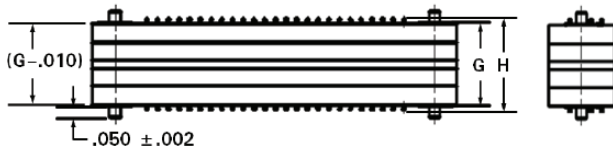
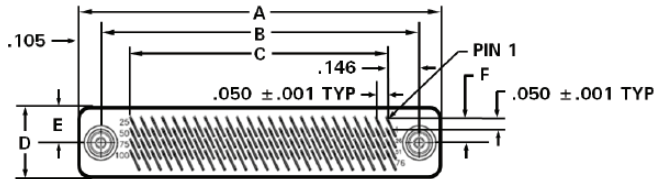
Contact Compression: 0.010 inches per side (nominal) for 0.100" and 0.150" connector heights; 0.015" per side (nominal) for 0.200", 0.250", 0.300" and 0.350" connector heights
 Compression Force: 25-40 grams per contact having a 0.010" deflection
 35-50 grams per contact having a 0.015" deflection
 Contact Wipe: ≈0.007" for 0.100" and 0.150" connector heights
 ≈0.014" for 0.200", 0.250", 0.300" and 0.350" connector heights
 Current Rating: 0.5 amperes
 Contact Resistance: 0.025 ohms typical (contact height-dependent)
 Operating Temperature: -65° C to +125° C
 Insulation Resistance: 5,000 megaohms minimum @ 100 VDC
 Durability: 50 connector mating cycles
 Dielectric Withstanding: 250 VDC @ sea level, 100 VDC @ altitude

NOTE: Performance values are estimates at this time. Actual values will be determined when final product testing is complete.



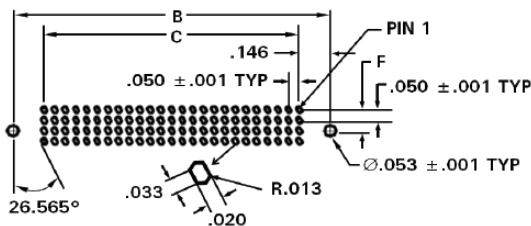
RZ DIMENSIONS

Guide Pin Hardware Option



DIMENSIONS								
SIZE	ROWS	COLS	A	B	C	D	E	F
20	2	10	0.952	0.742	0.450	0.210	0.105	0.050
30	2	15	1.202	0.992	0.700	0.210	0.105	0.050
40	2	20	1.452	1.242	0.950	0.210	0.105	0.050
50	2	25	1.702	1.492	1.200	0.210	0.105	0.050
30	3	10	0.952	0.742	0.450	0.260	0.105	0.050
45	3	15	1.202	0.992	0.700	0.260	0.105	0.050
60	3	20	1.452	1.242	0.950	0.260	0.105	0.050
75	3	25	1.702	1.492	1.200	0.260	0.105	0.050
40	4	10	0.952	0.742	0.450	0.310	0.155	0.100
60	4	15	1.202	0.992	0.700	0.310	0.155	0.100
80	4	20	1.452	1.242	0.950	0.310	0.155	0.100
100	4	25	1.702	1.492	1.200	0.310	0.155	0.100
50	5	10	0.952	0.742	0.450	0.360	0.155	0.100
75	5	15	1.202	0.992	0.700	0.360	0.155	0.100
100	5	20	1.452	1.242	0.950	0.360	0.155	0.100
125	5	25	1.702	1.492	1.200	0.360	0.155	0.100
60	6	10	0.952	0.742	0.450	0.410	0.205	0.150
90	6	15	1.202	0.992	0.700	0.410	0.205	0.150
120	6	20	1.452	1.242	0.950	0.410	0.205	0.150
150	6	25	1.702	1.492	1.200	0.410	0.205	0.150
70	7	10	0.952	0.742	0.450	0.460	0.205	0.150
105	7	15	1.202	0.992	0.700	0.460	0.205	0.150
140	7	20	1.452	1.242	0.950	0.460	0.205	0.150
175	7	25	1.702	1.492	1.200	0.460	0.205	0.150

PWB Layout



DIMENSIONS	
HARDWARE 'G'	CONTACT 'H'
0.100	0.120
0.150	0.170
0.200	0.230
0.250	0.280
0.300	0.330
0.350	0.380

Note: All dimensions are in inches.

PWB-PLATED PAD RECOMMENDATIONS:

Board to be made in accordance with ANSI/EIA-616

Laminate material per MIL-P-13949, Type GF

Copper foil thickness: 1 oz per square foot

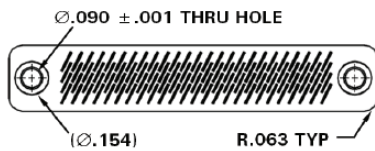
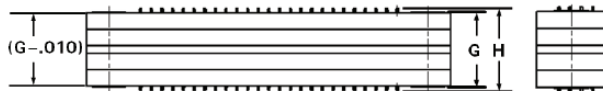
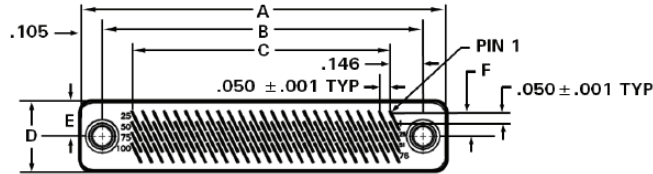
Plate all surface features with 50 μ", minimum, electrolytic hard gold over 50-150 μ" nickel.

(Optionally, plate all surface features with 50 μ", minimum, electrolytic hard gold over 5-10 μ" of electrolytic soft gold over 100 μ", minimum, nickel.)



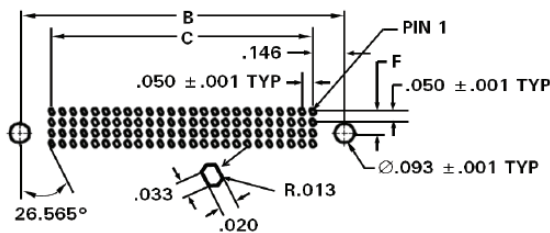
RZ DIMENSIONS

Thru-Hole Hardware Option



DIMENSIONS								
SIZE	ROWS	COLS	A	B	C	D	E	F
20	2	10	0.952	0.742	0.450	0.210	0.105	0.050
30	2	15	1.202	0.992	0.700	0.210	0.105	0.050
40	2	20	1.452	1.242	0.950	0.210	0.105	0.050
50	2	25	1.702	1.492	1.200	0.210	0.105	0.050
30	3	10	0.952	0.742	0.450	0.260	0.105	0.050
45	3	15	1.202	0.992	0.700	0.260	0.105	0.050
60	3	20	1.452	1.242	0.950	0.260	0.105	0.050
75	3	25	1.702	1.492	1.200	0.260	0.105	0.050
40	4	10	0.952	0.742	0.450	0.310	0.155	0.100
60	4	15	1.202	0.992	0.700	0.310	0.155	0.100
80	4	20	1.452	1.242	0.950	0.310	0.155	0.100
100	4	25	1.702	1.492	1.200	0.310	0.155	0.100
50	5	10	0.952	0.742	0.450	0.360	0.155	0.100
75	5	15	1.202	0.992	0.700	0.360	0.155	0.100
100	5	20	1.452	1.242	0.950	0.360	0.155	0.100
125	5	25	1.702	1.492	1.200	0.360	0.155	0.100
60	6	10	0.952	0.742	0.450	0.410	0.205	0.150
90	6	15	1.202	0.992	0.700	0.410	0.205	0.150
120	6	20	1.452	1.242	0.950	0.410	0.205	0.150
150	6	25	1.702	1.492	1.200	0.410	0.205	0.150
70	7	10	0.952	0.742	0.450	0.460	0.205	0.150
105	7	15	1.202	0.992	0.700	0.460	0.205	0.150
140	7	20	1.452	1.242	0.950	0.460	0.205	0.150
175	7	25	1.702	1.492	1.200	0.460	0.205	0.150

PWB Layout



DIMENSIONS	
HARDWARE 'G'	CONTACT 'H'
0.100	0.120
0.150	0.170
0.200	0.230
0.250	0.280
0.300	0.330
0.350	0.380

Note: All dimensions are in inches.

PWB-PLATED PAD RECOMMENDATIONS:

Board to be made in accordance with ANSI/EIA-616

Laminate material per MIL-P-13949, Type GF

Copper foil thickness: 1 oz per square foot

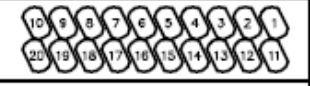
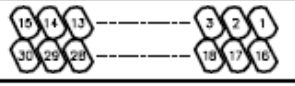
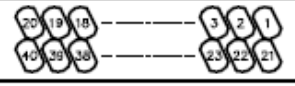
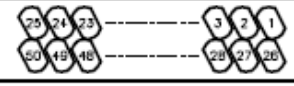

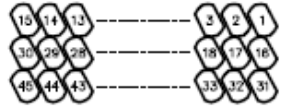



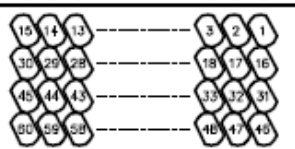




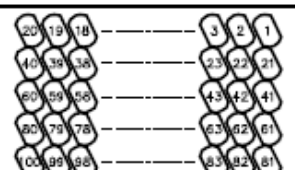



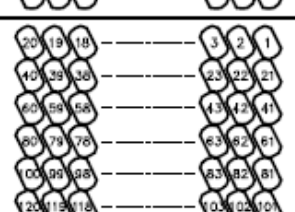
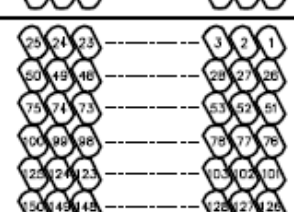
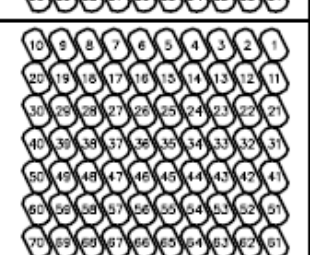
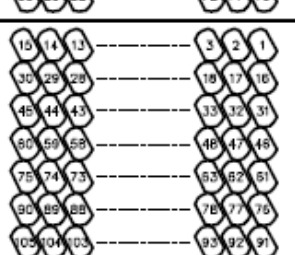
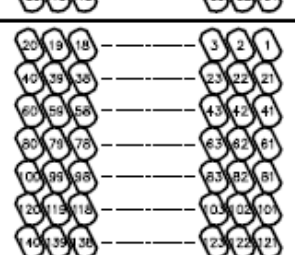
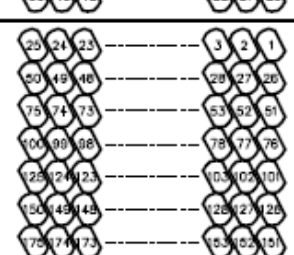
Plate all surface features with 50 μ", minimum, electrolytic hard gold over 50-150 μ" nickel.

(Optionally, plate all surface features with 50 μ", minimum, electrolytic hard gold over 5-10 μ" of electrolytic soft gold over 100 μ", minimum, nickel.)



RZ DRAWINGS

Board Footprint

CONTACT ID				
ROWS	COLUMNS			
	10	15	20	25
2				
3				
4				
5				
6				
7				

PWB-PLATED PAD RECOMMENDATIONS:

Board to be made in accordance with ANSI/EIA-616

Laminate material per MIL-P-13949, Type GF

Copper foil thickness: 1 oz per square foot

Plate all surface features with 50 μ ", minimum, electrolytic hard gold over 50-150 μ " nickel.

(Optionally, plate all surface features with 50 μ ", minimum, electrolytic hard gold over 5-10 μ " of electrolytic soft gold over 100 μ ", minimum, nickel.)